L Number	Hits	Search Text	DB	Time stamp
4	344	(((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) and ((wafer or substrate) with (bottom or (back adj side) with etch$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:29
5	323	(((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:29
6	64	((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch$3))) and 438/$3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:20
7	28	(((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch$3))) and 438/$3.ccls.) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
79	8	uv with tape with needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:31
80	11	(uv with tape) same needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:33
81	10	(ultraviolet with tape) same needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:39
82	72	(ultraviolet with adhesive) same needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:40
83	6	((ultraviolet with adhesive) same needle) same dic$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:03
84	7	(transfer adj tape) with (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 19:04
85	1389	(transfer adj tape) with (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30
86	6	((transfer adj tape) with (adhesive)) with dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:05
87	6	((transfer adj tape) with (adhesive)) same dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:05
88	11	(transfer adj tape) with dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:06
89	7	(transfer adj tape) same (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:28
90	15	((transfer adj tape) with (adhesive)) and 438/$3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30

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91	0	(pickup adj tape) same (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:28
92	2	(pickup adj tape) and (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:28
93	236	(dicing adj tape) with (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30
94	70	((dicing adj tape) with (adhesive)) and 438/$3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
95	24	(((dicing adj tape) with (adhesive)) and 438/$3.ccls.) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
96	6	(releas$3 adj tape) with (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 19:05
-	6	(dicing adj tape) same (transfer tape) same (etched adj ports)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:52
-	6	(dicing adj tape) with (through adj hole) with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:10
-	13	("4791075" | "4907065" | "5150196" | "5323051" | "5362681" | "5435876" | "5610431" | "5824177" | "5831162" | "6106735" | "6109113" | "6210514" | "6410360").PN.	USPAT	2003/11/12 18:09
-	6	(dicing adj tape) same (through adj hole) same backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:11
-	12	(dicing adj tape) and ((hole or via or open$3 or interconnect) with (substrate or wafer)) and (transfer adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:39
-	194	(dicing adj tape) and ((hole or via or open$3 or interconnect) with (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:40
-	53	(dicing adj tape) same ((hole or via or open$3 or interconnect) with (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:42
-	20	((dicing adj tape) same ((hole or via or open$3 or interconnect) with (substrate or wafer))) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
-	26	(dicing adj tape) with wafer with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:58
-	148	tape with wafer with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:59
-	246	tape with (wafer or substrate) with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 18:59

–	1713	(hole or open$3 or via or interconnect) with (wafer or substrate) with backside	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
–	38	(tape with (wafer or substrate) with backside) and ((hole or open$3 or via or interconnect) with (wafer or substrate) with backside)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
–	22	((tape with (wafer or substrate) with backside) and ((hole or open$3 or via or interconnect) with (wafer or substrate) with backside)) and dic$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
–	6	(((tape with (wafer or substrate) with backside) and ((hole or open$3 or via or interconnect) with (wafer or substrate) with backside)) and dic$3) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
–	2	5362681.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:56
–	56	5362681.URPN.	USPAT	2003/11/13 11:53
–	6315	((bottom or (back adj side)) with (tape or adhesive)) same (dic$3 or cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:57
–	469	((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:58
–	257327	(wafer or substrate) with (via hole open$3 interconnect)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:59
–	80	(((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) same ((wafer or substrate) with (via hole open$3 interconnect))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:27
–	0	((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) same ((wafer or substrate) with (via hole open$3 interconnect))) and 5362681.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:59
–	8	5362681.URPN. and (((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:29
–	1	007585.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 12:12
–	43	(((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate)) same (dic$3 or cut$4)) same ((wafer or substrate) with (via hole open$3 interconnect))) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 12:12
–	15	("4872825" | "4933744" | "5178957" | "5497033" | "5685885" | "5730922" | "5747101" | "5761801" | "5766979" | "5848467" | "5866952" | "5958995" | "5962608" | "5971253" | "6007407").PN.	USPAT	2003/11/13 12:35

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